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<ul> <li>State-of-the-Art Advanced BiCMOS Technology (ABT) Widebus™ Design for 2.5-V and 3.3-V Operation and Low Static</li> </ul>	SN54ALVTH16373 WD PACKAGE SN74ALVTH16373 DGG, DGV, OR DL PACKAGE (TOP VIEW)
Power Dissipation	
<ul> <li>Support Mixed-Mode Signal Operation (5-V</li> </ul>	1Q1 2 47 11D1
Input and Output Voltages With 2.3-V to	1Q2 🛛 <sub>3 46</sub> 🗍 1D2
3.6-V V <sub>CC</sub> )	GND 🛛 4 45 🗍 GND
<ul> <li>Typical V<sub>OLP</sub> (Output Ground Bounce)</li> </ul>	1Q3 🛛 5 44 🗋 1D3
< 0.8 V at V <sub>CC</sub> = 3.3 V, T <sub>A</sub> = 25°C	1Q4 🛛 <sub>6 43</sub> 🗍 1D4
<ul> <li>High Drive (–24/24 mA at 2.5-V and</li> </ul>	V <sub>CC</sub> [] 7 42 [] V <sub>CC</sub>
–32/64 mA at 3.3-V V <sub>CC</sub> )	1Q5 🛛 8 41 🖸 1D5
<ul> <li>Power Off Disables Outputs, Permitting</li> </ul>	1Q6 9 40 1D6
Live Insertion	
High-Impedance State During Power Up	
and Power Down Prevents Driver Conflict	1Q8 12 37 1D8
<ul> <li>Uses Bus Hold on Data Inputs in Place of</li> </ul>	2Q1 [] 13 36 [] 2D1
External Pullup/Pulldown Resistors to	2Q2 [ 14 35 ] 2D2
Prevent the Bus From Floating	GND [] 15 34 [] GND
<ul> <li>Auto3-State Eliminates Bus Current</li> </ul>	2Q3 [] <sub>16</sub> 33 [] 2D3 2Q4 [] <sub>17</sub> 32 [] 2D4
Loading When Output Exceeds V <sub>CC</sub> + 0.5 V	$V_{CC} \begin{bmatrix} 17 & 32 \\ 18 & 31 \end{bmatrix} V_{CC}$
<ul> <li>Latch-Up Performance Exceeds 250 mA Per</li> </ul>	2Q5 [] 19 30 [] 2D5
JESD 17	2Q6 20 29 2D6
	GND [21 28] GND
<ul> <li>ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V</li> </ul>	2Q7 22 27 2D7
Using Machine Model; and Exceeds 1000 V	2Q8 22 26 208

Using Charged-Device Model, Robotic Method

- Flow-Through Architecture Facilitates Printed Circuit Board Layout
- Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV) Packages, and 380-mil Fine-Pitch Ceramic Flat (WD) Package

#### description

The 'ALVTH16373 devices are 16-bit transparent D-type latches with 3-state outputs designed for 2.5-V or 3.3-V  $V_{CC}$  operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

These devices can be used as two 8-bit latches or one 16-bit latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.



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### description (continued)

A buffered output-enable ( $\overline{OE}$ ) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When  $V_{CC}$  is between 0 and 1.2 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.2 V, OE should be tied to V<sub>CC</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ALVTH16373 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALVTH16373 is characterized for operation from -40°C to 85°C.

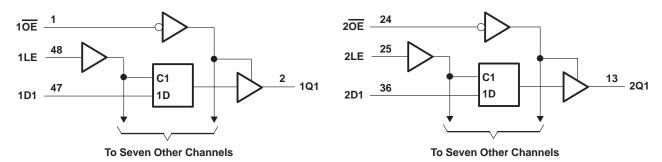
	(each o	-DIL Sect	.1011)
	INPUTS		OUTPUT
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Х	Q <sub>0</sub>
н	Х	Х	Z

**FUNCTION TABLE** (oach 8-bit soction)



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### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	
Input voltage range, V <sub>I</sub> (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance	
or power-off state, V <sub>O</sub> (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, V <sub>O</sub> (see Note 1)	–0.5 V to 7 V
Output current in the low state, I <sub>O</sub> : SN54ALVTH16373	96 mA
SN74ALVTH16373	
Output current in the high state, I <sub>O</sub> : SN54ALVTH16373	–48 mA
SN74ALVTH16373	
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ )	
Package thermal impedance, $\theta_{JA}$ (see Note 2): DGG package	
DGV package	
DL package	
Storage temperature range, T <sub>stg</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51.

### recommended operating conditions, $V_{CC}$ = 2.5 V ± 0.2 V (see Note 3)

			SN54	ALVTH1	6373	SN74	ALVTH1	6373	UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
VCC	Supply voltage		2.3		2.7	2.3		2.7	V
VIH	High-level input voltage	1.7			1.7			V	
VIL	Low-level input voltage		14	0.7			0.7	V	
VI	Input voltage	0	Vcc	5.5	0	VCC	5.5	V	
ЮН	High-level output current			Q	-6			-8	mA
	Low-level output current			(C)	6			8	mA
IOL	Low-level output current; current duty cycle $\leq$	50%; f ≥ 1 kHz	5	5	18			24	ША
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled	5		10			10	ns/V
Δt/ΔV <sub>CC</sub>	Power-up ramp rate	200			200			μs/V	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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## recommended operating conditions, V\_CC = 3.3 V $\pm$ 0.3 V (see Note 3)

			SN54	ALVTH16	6373	SN74	ALVTH1	6373	UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
VCC	Supply voltage		3		3.6	3		3.6	V
VIH	High-level input voltage	2			2			V	
VIL	Low-level input voltage		4	0.8			0.8	V	
VI	Input voltage	0	Vcc	5.5	0	VCC	5.5	V	
IOH	High-level output current			Q	-24			-32	mA
	Low-level output current			(C)	24			32	mA
IOL	Low-level output current; current duty cycle $\leq$	50%; f ≥ 1 kHz	~	2	48			64	ША
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled	4	/	10			10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200			200			μs/V	
TA	Operating free-air temperature	-55		125	-40		85	°C	

NOTE 3: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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## electrical characteristics over recommended operating free-air temperature range, $V_{CC}$ = 2.5 V $\pm$ 0.2 V (unless otherwise noted)

D		TEST	ONDITIONS	SN54	ALVTH1	6373	SN74	ALVTH1	6373	UNIT	
P/	ARAMETER	IESIC	ONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT	
Vik		V <sub>CC</sub> = 2.3 V,	lj = -18 mA			-1.2			-1.2	V	
		$V_{CC}$ = 2.3 V to 2.7 V,	l <sub>OH</sub> = –100 μA	V <sub>CC</sub> -0	.2		V <sub>CC</sub> -0	.2			
Vон			I <sub>OH</sub> = -6 mA	1.8						V	
		V <sub>CC</sub> = 2.3 V	I <sub>OH</sub> = -8 mA				1.8				
		$V_{CC}$ = 2.3 V to 2.7 V,	l <sub>OL</sub> = 100 μA			0.2			0.2		
			I <sub>OL</sub> = 6 mA			0.4					
Vol			I <sub>OL</sub> = 8 mA						0.4	V	
		$V_{CC} = 2.3 V$	I <sub>OL</sub> = 18 mA			0.5					
			I <sub>OL</sub> = 24 mA					0.5			
Control inputs		V <sub>CC</sub> = 2.7 V,	$V_I = V_{CC}$ or GND			±1			±1		
	Control inputs	V <sub>CC</sub> = 0 or 2.7 V,	V <sub>I</sub> = 5.5 V			\$ 10			10		
lj –			VI = 5.5 V		1	10			10	μΑ	
[	Data inputs	V <sub>CC</sub> = 2.7 V	$V_I = V_{CC}$		R	1			1		
			$V_{I} = 0$		4	-5			-5		
loff	-	V <sub>CC</sub> = 0,	$V_{I} \text{ or } V_{O} = 0 \text{ to } 4.5 \text{ V}$		2				±100	μΑ	
I <sub>BHL</sub> ‡		V <sub>CC</sub> = 2.3 V,	V <sub>I</sub> = 0.7 V		115			115		μΑ	
I <sub>BHH</sub> §		V <sub>CC</sub> = 2.3 V,	V <sub>I</sub> = 1.7 V	Q	-10			-10		μΑ	
BHLC		V <sub>CC</sub> = 2.7 V,	$V_{I} = 0$ to $V_{CC}$	300			300			μΑ	
Івнно		V <sub>CC</sub> = 2.7 V,	$V_{I} = 0$ to $V_{CC}$	-300			-300			μΑ	
IEX		V <sub>CC</sub> = 2.3 V,	V <sub>O</sub> = 5.5 V			125			125	μΑ	
IOZ(P	U/PD)☆	$V_{CC} \le 1.2 \text{ V}, \text{ V}_{O} = \frac{0.5}{\text{OE}}$ V <sub>I</sub> = GND or V <sub>CC</sub> , $\overline{\text{OE}}$	V to V <sub>CC</sub> , = don't care			±100			±100	μA	
IOZH		V <sub>CC</sub> = 2.7 V	V <sub>O</sub> = 2.3 V, V <sub>I</sub> = 0.7 V or 1.7 V			5			5	μA	
IOZL		V <sub>CC</sub> = 2.7 V	$V_{O} = 0.5 V,$ $V_{I} = 0.7 V \text{ or } 1.7 V$			-5			-5	μA	
		Vec = 2.7.V	Outputs high		0.04	0.1		0.04	0.1		
ICC		$V_{CC} = 2.7 V,$ I <sub>O</sub> = 0,	Outputs low	1	2.3	4.5		2.3	4.5	mA	
00		$V_{I} = V_{CC}$ or GND	Outputs disabled	1	0.04	0.1		0.04	0.1		
Ci		V <sub>CC</sub> = 2.5 V,	V <sub>I</sub> = 2.5 V or 0	1	3.5			3.5		pF	
Co		$V_{CC} = 2.5 V,$	$V_{0} = 2.5 \text{ V or } 0$		6		<u> </u>	6		pF	

<sup>†</sup> All typical values are at  $V_{CC} = 2.5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>‡</sup> The bus-hold circuit can sink at least the minimum low sustaining current at V<sub>IL</sub> max. I<sub>BHL</sub> should be measured after lowering V<sub>IN</sub> to GND and then raising it to V<sub>IL</sub> max.

§ The bus-hold circuit can source at least the minimum high sustaining current at V<sub>IH</sub> min. IBHH should be measured after raising V<sub>IN</sub> to V<sub>CC</sub> and then lowering it to V<sub>IH</sub> min.

 $\P$  An external driver must source at least IBHLO to switch this node from low to high.

<sup>#</sup> An external driver must sink at least IBHHO to switch this node from high to low.

I Current into an output in the high state when  $V_O > V_{CC}$ 

\*High-impedance state during power up or power down



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## electrical characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted)

P	ARAMETER	TEAT	CONDITIONS	SN54/	ALVTH1	6373	SN74	ALVTH1	6373	UNIT	
P/	ARAMETER	IESIC	CONDITIONS	MIN	TYP†	MAX	MIN	TYP <sup>†</sup>	MAX	UNII	
Vik		V <sub>CC</sub> = 3 V,	lj = -18 mA			-1.2			-1.2	V	
		V <sub>CC</sub> = 3 V to 3.6 V,	I <sub>OH</sub> = -100 μA	V <sub>CC</sub> -0.	2		V <sub>CC</sub> -0.	.2			
Vон			I <sub>OH</sub> = -24 mA	2						V	
		VCC = 3 V	I <sub>OH</sub> = -32 mA			2					
		V <sub>CC</sub> = 3 V to 3.6 V,	I <sub>OL</sub> = 100 μA			0.2			0.2		
			I <sub>OL</sub> = 16 mA						0.4		
			I <sub>OL</sub> = 24 mA			0.5				V	
V <sub>OL</sub>		$V_{CC} = 3 V$	I <sub>OL</sub> = 32 mA						0.5	V	
		I <sub>OL</sub> = 48 mA			0.55						
			I <sub>OL</sub> = 64 mA						0.55		
	Control inputs	V <sub>CC</sub> = 3.6 V,	$V_I = V_{CC} \text{ or } GND$			A ±1			±1		
	Control inputs	V <sub>CC</sub> = 0 or 3.6 V,	V <sub>I</sub> = 5.5 V			10			10		
lj –			VI = 5.5 V		RE	10			10	μΑ	
	Data inputs	V <sub>CC</sub> = 3.6 V	$V_{I} = V_{CC}$		1	1			1		
			$V_{I} = 0$		2	-5			-5		
loff		$V_{CC} = 0,$	$V_{I}$ or $V_{O}$ = 0 to 4.5 V		5				±100	μΑ	
I <sub>BHL</sub> ‡	:	V <sub>CC</sub> = 3 V,	VI = 0.8 V	75			75			μΑ	
I <sub>BHH</sub> §	Ì	V <sub>CC</sub> = 3 V,	V <sub>I</sub> = 2 V	-75			-75			μΑ	
BHLC		V <sub>CC</sub> = 3.6 V,	$V_I = 0$ to $V_{CC}$	500			500			μA	
Івнно	D <sup>#</sup>	V <sub>CC</sub> = 3.6 V,	$V_{I} = 0$ to $V_{CC}$	-500			-500			μA	
I <sub>EX</sub>		V <sub>CC</sub> = 3 V,	V <sub>O</sub> = 5.5 V			125			125	μΑ	
I <sub>OZ(P</sub>	U/PD)☆	$V_{CC} \le 1.2 \text{ V}, V_O = \frac{0.5}{0.5}$ $V_I = \text{GND or } V_{CC}, \overline{\text{OE}}$	V to V <sub>CC</sub> , = don't care			±100			±100	μA	
IOZH		V <sub>CC</sub> = 3.6 V	V <sub>O</sub> = 3 V, V <sub>I</sub> = 0.8 V or 2 V			5			5	μA	
I <sub>OZL</sub>		V <sub>CC</sub> = 3.6 V	$V_{O} = 0.5 V,$ $V_{I} = 0.8 V \text{ or } 2 V$			-5			-5	μA	
		V <sub>CC</sub> = 3.6 V,	Outputs high		0.07	0.1		0.07	0.1		
ICC		$I_{O} = 0,$	Outputs low		3.2	5.5		3.2	5	mA	
		$V_{I} = V_{CC}$ or GND	Outputs disabled		0.07	0.1		0.07	0.1		
∆ICC□	]	$V_{CC} = 3 V$ to 3.6 V, Or Other inputs at $V_{CC}$ or	e input at V <sub>CC</sub> – 0.6 V, GND			0.4			0.4	mA	
Ci		V <sub>CC</sub> = 3.3 V,	V <sub>I</sub> = 3.3 V or 0		3.5			3.5		pF	
Co		V <sub>CC</sub> = 3.3 V,	V <sub>O</sub> = 3.3 V or 0		6			6		pF	

<sup>†</sup> All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> =  $25^{\circ}$ C.

<sup>‡</sup> The bus-hold circuit can sink at least the minimum low sustaining current at V<sub>IL</sub> max. I<sub>BHL</sub> should be measured after lowering V<sub>IN</sub> to GND and then raising it to V<sub>II</sub> max.

S The bus-hold circuit can source at least the minimum high sustaining current at V<sub>IH</sub> min. I<sub>BHH</sub> should be measured after raising V<sub>IN</sub> to V<sub>CC</sub> and then lowering it to V<sub>IH</sub> min.

 $\P$  An external driver must source at least  $I_{BHLO}$  to switch this node from low to high.

<sup>#</sup> An external driver must sink at least IBHHO to switch this node from high to low.

I Current into an output in the high state when  $V_O > V_{CC}$ 

\*High-impedance state during power up or power down

□ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

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### timing requirements over recommended operating free-air temperature range, V<sub>CC</sub> = 2.5 V $\pm$ 0.2 V (unless otherwise noted) (see Figure 1)

			SN54ALVTH16373	SN74ALVTH16373	UNIT		
			MIN MAX	MIN MAX			
tw	Pulse duration, LE high	Pulse duration, LE high					
		Data high 1.1		1			
t <sub>su</sub>	Setup time, data before LE $\downarrow$	Data low	1.6	1.5	ns		
t.	Hold time, data after LE $\downarrow$	Data high	Q1	0.9			
<sup>t</sup> h	Hold time, data after LE $\downarrow$	1.6	1.5	ns			

### timing requirements over recommended operating free-air temperature range, V<sub>CC</sub> = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 2)

			SN54ALVTH16373	SN74ALVTH16373	UNIT
			MIN MAX	MIN MAX	
tw	Pulse duration, LE high	1.5 🖉	1.5	ns	
		Data high	1.5	1.4	
t <sub>su</sub>	Setup time, data before LE $\downarrow$	Data low	e l	0.9	ns
t.	Hold time, data after LE $\downarrow$	Data high	Q1	0.9	ns
t <sub>h</sub>	Hold time, data alter LEV	Data low	1.5	1.4	115

# switching characteristics over recommended operating free-air temperature range, C<sub>L</sub> = 30 pF, V<sub>CC</sub> = 2.5 V $\pm$ 0.2 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	SN54ALVTH16373	SN74ALVTH16373	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN MAX	MIN MAX	
<sup>t</sup> PLH	D	Q	1 3.4	1 3.3	ns
<sup>t</sup> PHL	D	Q	1 4.3	1 4.2	115
<sup>t</sup> PLH	LE	Q	1.4 🐊 3.9	1.5 3.8	ns
<sup>t</sup> PHL	LL	Q	1.4 4.6	1.5 4.5	115
<sup>t</sup> PZH	OE	Q	1.7 4.4	1.8 4.3	ns
<sup>t</sup> PZL	UE	Q	1,4 4.1	1.5 4	115
<sup>t</sup> PHZ	OE	Q	1.4 4.7	1.5 4.6	ns
<sup>t</sup> PLZ	UE	y y	1 3.7	1 3.6	113

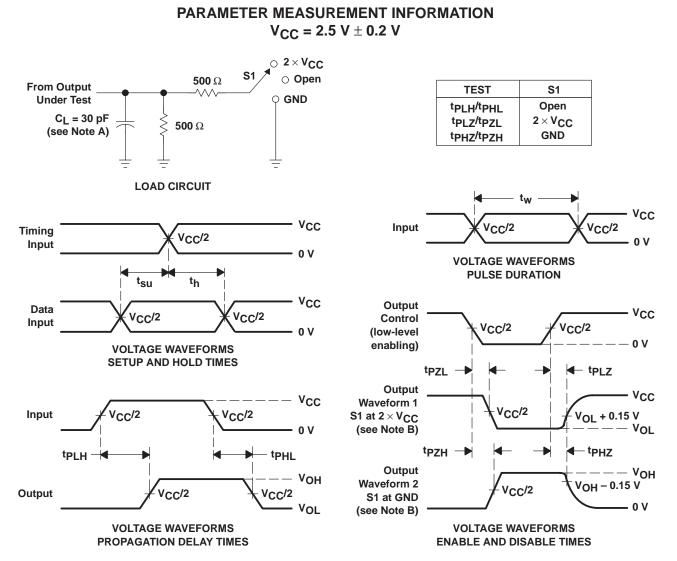
# switching characteristics over recommended operating free-air temperature range, C<sub>L</sub> = 50 pF, V<sub>CC</sub> = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 2)

PARAMETER	FROM	то	SN54ALVTH1	6373	SN74ALVT	H16373	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX		
<sup>t</sup> PLH	D	Q	1	3.2	1	3.1	20	
<sup>t</sup> PHL	U	Q	1	3.4	1	3.3	ns	
<sup>t</sup> PLH	LE	Q	1	3.4	1	3.3	ns	
<sup>t</sup> PHL	LL	Q	1 2	3.6	1	3.5	115	
<sup>t</sup> PZH	OE	Q	1.3	4.1	1.4	4	20	
<sup>t</sup> PZL	UE	Q	70	3.5	1	3.4	ns	
<sup>t</sup> PHZ	OE	0	Q~1.4	5	1.5	4.9	ns	
<sup>t</sup> PLZ	UE	Q	1.4	4.6	1.5	4.5	115	

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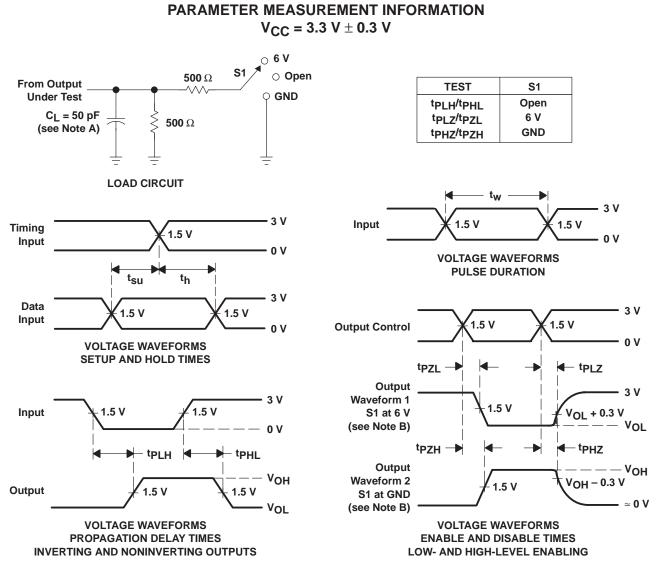


- NOTES: A. CL includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
     C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>Q</sub> = 50 Ω, t<sub>f</sub> ≤ 2 ns, t<sub>f</sub> ≤ 2 ns.
  - D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform22 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50 Ω, t<sub>f</sub>  $\leq$  2.5 ns. t<sub>f</sub>  $\leq$  2.5 ns.
  - D. The outputs are measured one at a time with one transition per measurement.

The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms





### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
74ALVTH16373VRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	VT373	Samples
SN74ALVTH16373DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVTH16373	Samples
SN74ALVTH16373DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVTH16373	Samples
SN74ALVTH16373GR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVTH16373	Samples
SN74ALVTH16373VR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	VT373	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



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## PACKAGE MATERIALS INFORMATION

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### TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVTH16373DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN74ALVTH16373GR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ALVTH16373VR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1

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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVTH16373DLR	SSOP	DL	48	1000	367.0	367.0	55.0
SN74ALVTH16373GR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74ALVTH16373VR	TVSOP	DGV	48	2000	367.0	367.0	38.0

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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## **MECHANICAL DATA**

PLASTIC SMALL-OUTLINE

MPDS006C - FEBRUARY 1996 - REVISED AUGUST 2000

### DGV (R-PDSO-G\*\*)

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153

14/16/20/56 Pins – MO-194



## **MECHANICAL DATA**

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

### DGG (R-PDSO-G\*\*)

### PLASTIC SMALL-OUTLINE PACKAGE

**48 PINS SHOWN** 



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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